12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20041217000
Shipping Tray change for 16x16mm Micro*BGA
Final Change Notification

Dear Customer:

This is a final announcement of change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

This notice does not apply to product on end-of-life status. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

The changes discussed within this PCN will not take affect any earlier than **30** days from the date of this notification. This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: (214) 480-6037
Fax: (214) 480-6659

PCN Number:	20041217000	**PCN Date:**	01/14/2005
Title:	Shipping Tray change for 16x16mm Micro*BGA		

Customer Contact:	PCN Manager (PCN_ww_admin_team@list.ti.com)	**Phone:**	(214) 480-6037	**Dept:**	Quality Services
Proposed 1st Ship Date:	04/14/2005	**Estimated Sample Availability date:**		01/14/2005	

Change Type:

☐ Assembly Site	☐ Assembly Process	☐ Assembly Materials
☐ Design	☐ Electrical Specification	☐ Mechanical Specification
☐ Test Site	☒ Packing / Shipping / Labeling	☐ Test Process
☐ Wafer Bump Site	☐ Wafer Bump Material	☐ Wafer Bump Process
☐ Wafer Fab Site	☐ Wafer Fab Materials	☐ Wafer Fab Process

PCN Details

Description of Change:

TI's assembly / test site in Japan will introduce a new tray for devices in the 16 x 16mm microstar BGA package. Critical dimensions such as outer dimension, pocket pitch, pocket size, tray matrix and unit seating height in pocket on the new tray are the same as on the current tray.

The only dimensional change which may affect customers is the tray stacking height, which is the overlap between the upper tray and lower tray when they are stacked (see diagram on last page). The current tray has a stack height of 1.27mm, whereas the new tray stack height is 2.0mm.

Reason for Change:

Reduce the tray warpage and eliminate "stuck tray" problem.

Product Affected:

F721681AGHK	PCI2050ZHK	PCI7610GHK	TMC57128GJG
F722500BGHK	PCI2060GHK	PCI7620GHK	TMC57931GGHK
F741923AGHK	PCI4410AGHK	PCI7620ZHK	TMC57931KGHK
NETC2DSC11GHK	PCI4410GHK	SN0211040GHK	TMC57934AGJG
PCI1225GHK	PCI4450GJG	SN0301018GHK	TMC57934AZJG
PCI1251BGJG	PCI4451GJG	SN0301510GHK	TMC57B04EGHK
PCI1410AGHK	PCI4510AGHK	SN0301520GHK	TMS320DSC24GHK-D
PCI1410GHK	PCI4510AZHK	SN0302023GHK	TMS320DSC24GHK-DPA
PCI1420GHK	PCI4510GHK	SN0303053GHK	TMS320DSC24GHK-L
PCI1450GJG	PCI4510ZHK	SN0304510GHK	TMS320DSC24ZHK-L
PCI1451AGJG	PCI4520GHK	SN0304520GHK	TMS320DSC25GHK
PCI1451GJG	PCI4520ZHK	SN0307009BGHK	TMS320DSC25GHK-B
PCI1520GHK	PCI6420GHK	SN0307009BZHK	TMS320DSC25GHK-C
PCI1520IGHK	PCI6420ZHK	SN0307009GHK	TMS320DSC25ZHK
PCI1520ZHK	PCI6620GHK	SN0307009ZHK	TMX320DSC24GHK-C
PCI1620GHK	PCI6620ZHK	SN0307420GHK	TMX320DSC25GHK-A
PCI2050BGHK	PCI7410GHK	SN0307420ZHK	TMX57128BGJG-1
PCI2050BIGHK	PCI7420BZHK	SN0308037GHK	TNETD4100GJG
PCI2050GHK	PCI7420GHK	SN0308037ZHK	TNETD4150GJG
PCI2050IGHK	PCI7420ZHK	SN105095GHK	XF731754FGHK
	PCI7510GHK	SN105095ZHK	

Anticipate (positive / negative) impact on Fit, Form, Function & Reliability:

There is no impact with regards to the device performance or reliability. The change will improve the performance of the trays during handling in the factory.

Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qualification Schedule:	**Start:**		**End:**	10/11/04
Qualification: ☐ **Plan** ☒ **Test Results**				

Reliability Test	Conditions	Sample size (Accept #)	Results (Pass/Fail)
Bake Test	20 tray strapped stack; 150degC / 8 hours; 5 cycles with Al plates	20 trays (0 fails)	Pass
Drop Test	30 inch height; 7 times	1 box, 2 bags (0 fails)	Pass
Manufacturability	IC fitting	10 trays (0 fails)	Pass
	Tray fitting		
	- Trim M/C	10 trays (0 fails)	Pass
	- Test Handler	10 trays (0 fails)	Pass
	- Vision system	10 trays (0 fails)	Pass
Visual/mechanical	Naked eye	20 trays (0 fails)	Pass
Surface resistivity	Digital insulation tester	15 trays stack	Pass
Dimensional Analysis	3 Dimensional measurements (include after 48hrs bake)	10 trays (0 fails)	Pass
Design Fit Analysis	3 Dimensional measurements	10 units (0 fails)	Pass

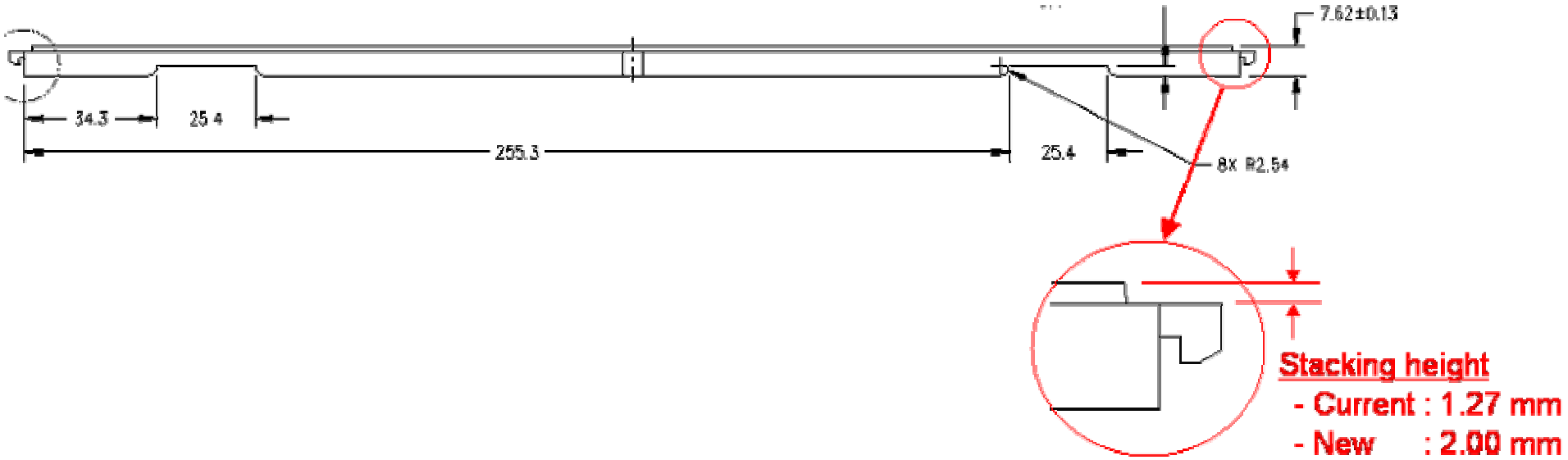
Product Identification

There is no change to the product identification as a result of this tray change.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

Diagram of Change to Tray Stacking Height



End of notice